

PHP32N06LT; PHB32N06LT

N-channel enhancement mode field effect transistor

Rev. 01 — 06 November 2001

Product data

1. Description

N-channel enhancement mode field-effect power transistor in a plastic package using TrenchMOS™¹ technology.

Product availability:

PHP32N06LT in SOT78 (TO220AB)

PHB32N06LT in SOT404 (D²-PAK).

2. Features

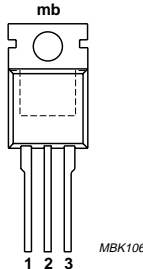
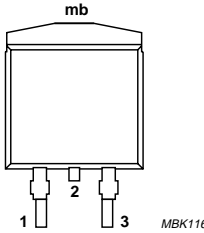
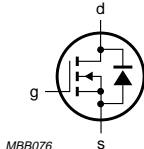
- TrenchMOS™ technology
- Logic level compatible.

3. Applications

- General purpose switching
- Switched mode power supplies.

4. Pinning information

Table 1: Pinning - SOT78 (TO-220AB), SOT404 (D²-PAK), simplified outline and symbol

| Pin | Description | Simplified outline | | Symbol |
|-----|--|---|--|---|
| 1 | gate (g) |  |  |  |
| 2 | drain (d) | | | |
| 3 | source (s) | | | |
| mb | mounting base; connected to drain (d) | | | |
| | | SOT78 (TO-220AB) | SOT404 (D ² -PAK) | |

[1] It is not possible to make connection to pin 2 of the SOT404 package.

1. TrenchMOS is a trademark of Koninklijke Philips Electronics N.V.

5. Quick reference data

Table 2: Quick reference data

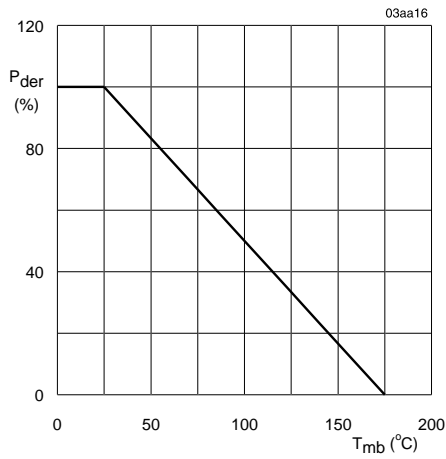
| Symbol | Parameter | Conditions | Typ | Max | Unit |
|--------------|----------------------------------|--|-----|-----|------|
| V_{DS} | drain-source voltage (DC) | | - | 60 | V |
| I_D | drain current (DC) | $T_{mb} = 25\text{ °C}$; $V_{GS} = 5\text{ V}$ | - | 34 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$ | - | 97 | W |
| T_j | junction temperature | | - | 175 | °C |
| $R_{DS(on)}$ | drain-source on-state resistance | $T_j = 25\text{ °C}$; $V_{GS} = 5\text{ V}$; $I_D = 20\text{ A}$ | 30 | 40 | mΩ |
| | | $T_j = 25\text{ °C}$; $V_{GS} = 4.5\text{ V}$; $I_D = 20\text{ A}$ | - | 43 | mΩ |

6. Limiting values

Table 3: Limiting values

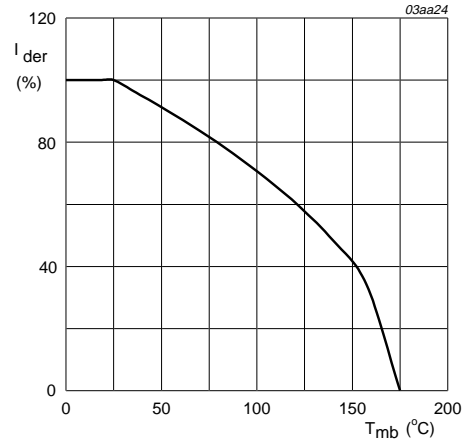
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|------------------------------------|--|-----|----------|------|
| V_{DS} | drain-source voltage (DC) | | - | 60 | V |
| V_{DGR} | drain-gate voltage (DC) | $R_{GS} = 20\text{ k}\Omega$ | - | 60 | V |
| V_{GS} | gate-source voltage (DC) | | - | ± 15 | V |
| V_{GSM} | non-repetitive gate-source voltage | $t_p \leq 50\text{ }\mu\text{s}$ | - | ± 20 | V |
| I_D | drain current (DC) | $T_{mb} = 25\text{ °C}$; $V_{GS} = 5\text{ V}$; Figure 2 and 3 | - | 34 | A |
| | | $T_{mb} = 100\text{ °C}$; $V_{GS} = 5\text{ V}$; Figure 2 | - | 24 | A |
| I_{DM} | peak drain current | $T_{mb} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; Figure 3 | - | 136 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$; Figure 1 | - | 97 | W |
| T_{stg} | storage temperature | | -55 | +175 | °C |
| T_j | operating junction temperature | | -55 | +175 | °C |
| Source-drain diode | | | | | |
| I_S | reverse drain current (DC) | $T_{mb} = 25\text{ °C}$ | - | 34 | A |
| I_{SM} | pulsed reverse drain current | $T_{mb} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ | - | 136 | A |
| Avalanche ruggedness | | | | | |
| W_{DSS} | non-repetitive avalanche energy | unclamped inductive load; $I_D = 20\text{ A}$; $t_p = 0.11\text{ ms}$; $V_{DS} \leq 25\text{ V}$; $V_{GS} = 5\text{ V}$; $R_{GS} = 50\text{ }\Omega$; starting $T_j = 25\text{ °C}$ | - | 100 | mJ |



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

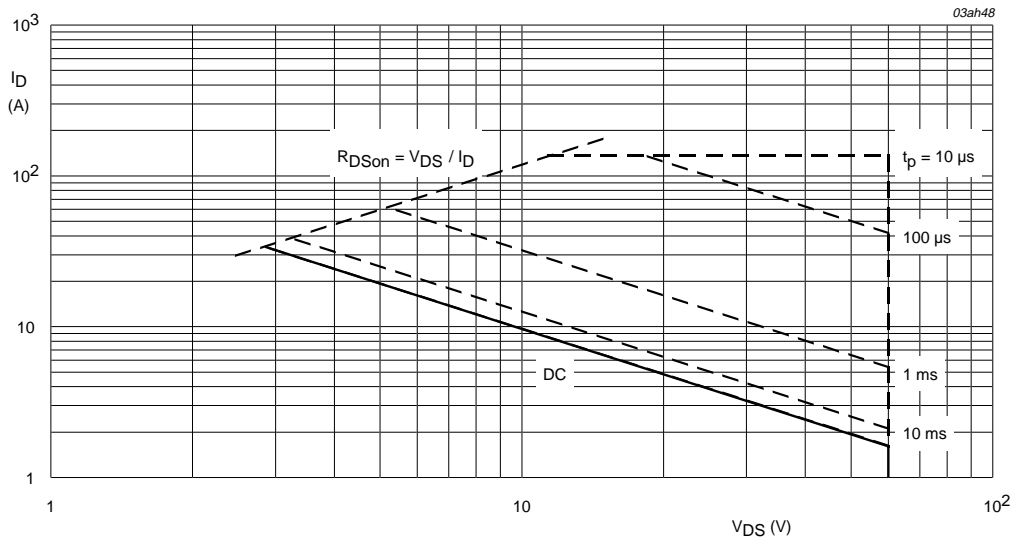
Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$V_{GS} \geq 4.5 \text{ V}$$

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



$T_{amb} = 25^{\circ}C$; I_{DM} is single pulse.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

7. Thermal characteristics

Table 4: Thermal characteristics

| Symbol | Parameter | Conditions | Value | Unit |
|----------------|---|--|-------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | vertical in still air; SOT78 package | 60 | K/W |
| | | mounted on printed circuit board; minimum footprint; SOT404 package | 50 | K/W |
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Figure 4 | 1.55 | K/W |

7.1 Transient thermal impedance

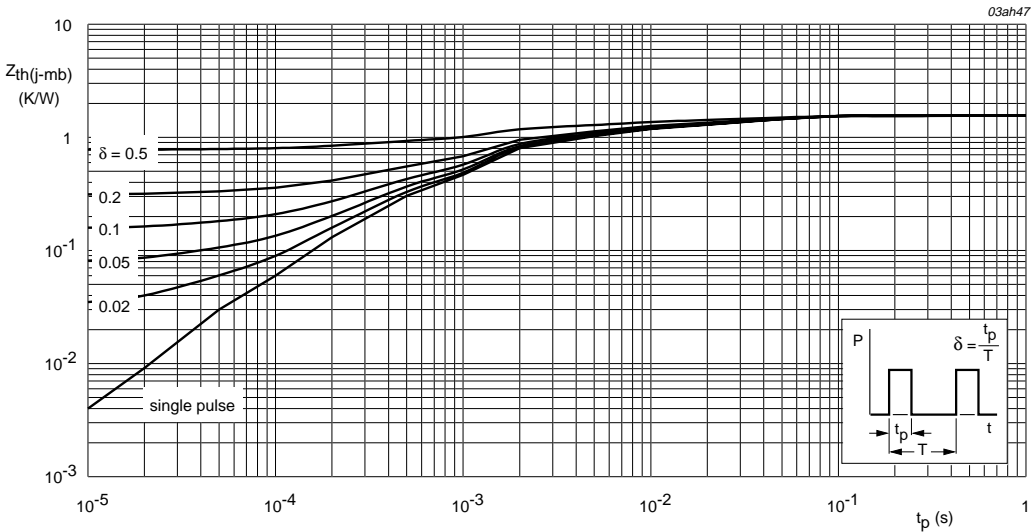


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration.

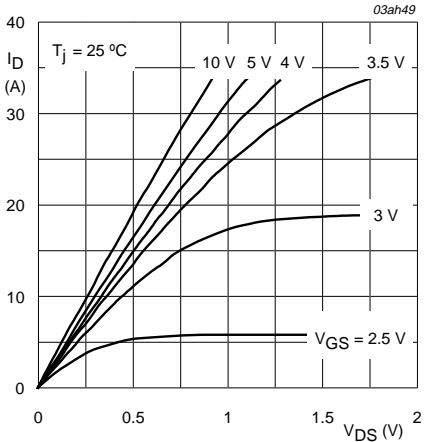
8. Characteristics

Table 5: Characteristics
 $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|-----|------|------|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 0.25\text{ mA}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^{\circ}\text{C}$ | 60 | - | - | V |
| | | $T_j = -55\text{ }^{\circ}\text{C}$ | 55 | - | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$; Figure 9 $T_j = 25\text{ }^{\circ}\text{C}$ | 1 | 1.5 | 2 | V |
| | | $T_j = 175\text{ }^{\circ}\text{C}$ | 0.5 | - | - | V |
| | | $T_j = -55\text{ }^{\circ}\text{C}$ | - | - | 2.3 | V |
| I_{DSS} | drain-source leakage current | $V_{DS} = 60\text{ V}$; $V_{GS} = 0\text{ V}$ $T_j = 25\text{ }^{\circ}\text{C}$ | - | 0.05 | 10 | μA |
| | | $T_j = 175\text{ }^{\circ}\text{C}$ | - | - | 500 | μA |
| I_{GSS} | gate-source leakage current | $V_{GS} = \pm 10\text{ V}$; $V_{DS} = 0\text{ V}$ | - | 2 | 100 | nA |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 5\text{ V}$; $I_D = 20\text{ A}$; Figure 7 and 8 $T_j = 25\text{ }^{\circ}\text{C}$ | - | 30 | 40 | m Ω |
| | | $T_j = 175\text{ }^{\circ}\text{C}$ | - | - | 84 | m Ω |
| | | $V_{GS} = 4.5\text{ V}$; $I_D = 20\text{ A}$; | - | 31.5 | 43 | m Ω |
| | | $V_{GS} = 10\text{ V}$; $I_D = 20\text{ A}$; | - | 26 | 37 | m Ω |
| Dynamic characteristics | | | | | | |
| $Q_{g(tot)}$ | total gate charge | $I_D = 20\text{ A}$; $V_{DD} = 44\text{ V}$; $V_{GS} = 5\text{ V}$; Figure 13 | - | 17 | - | nC |
| Q_{gs} | gate-source charge | | - | 3 | - | nC |
| Q_{gd} | gate-drain (Miller) charge | | - | 8.5 | - | nC |
| C_{iss} | input capacitance | $V_{GS} = 0\text{ V}$; $V_{DS} = 25\text{ V}$; $f = 1\text{ MHz}$; Figure 11 | - | 920 | 1280 | pF |
| C_{oss} | output capacitance | | - | 160 | 200 | pF |
| C_{rss} | reverse transfer capacitance | | - | 100 | 155 | pF |
| $t_{d(on)}$ | turn-on delay time | $V_{DS} = 30\text{ V}$; $R_L = 1.2\text{ }\Omega$; $V_{GS} = 5\text{ V}$; $R_G = 10\text{ }\Omega$; | - | 14 | - | ns |
| t_r | rise time | | - | 120 | - | ns |
| $t_{d(off)}$ | turn-off delay time | | - | 45 | - | ns |
| t_f | fall time | | - | 55 | - | ns |

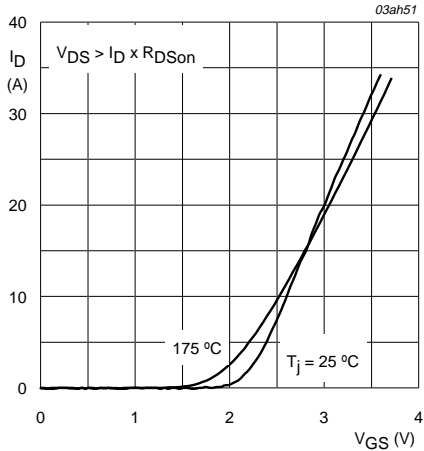
Table 5: Characteristics...continued
 $T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------|--------------------------------------|---|-----|-----|-----|------|
| Source-drain diode | | | | | | |
| V_{SD} | source-drain (diode forward) voltage | $I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 12 | - | 1 | 1.2 | V |
| t_{rr} | reverse recovery time | $I_S = 20\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$ | - | 36 | - | ns |
| Q_r | recovered charge | $V_{GS} = -10\text{ V}$; $V_{DS} = 30\text{ V}$ | - | 70 | - | nC |



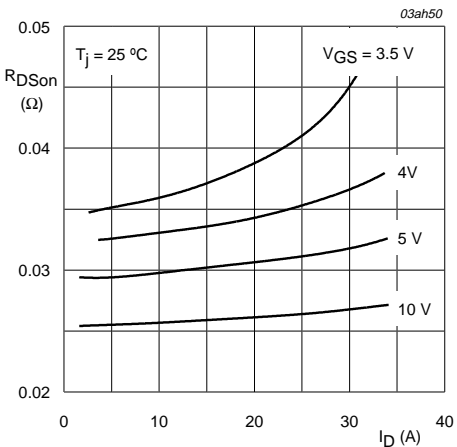
$T_j = 25\text{ }^{\circ}\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



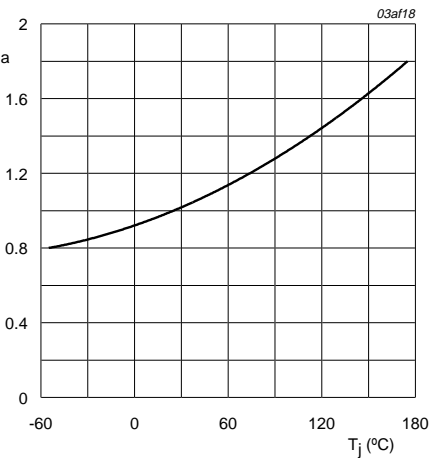
$T_j = 25\text{ }^{\circ}\text{C}$ and $175\text{ }^{\circ}\text{C}$; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



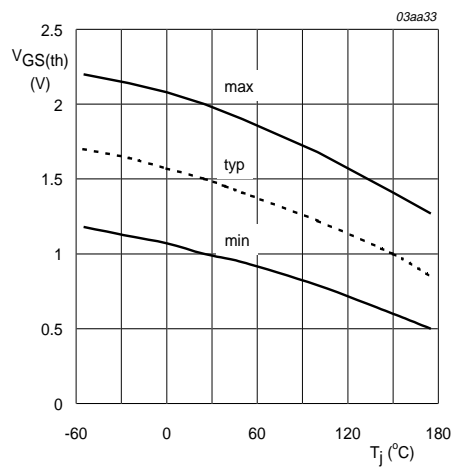
$T_j = 25\text{ }^{\circ}\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



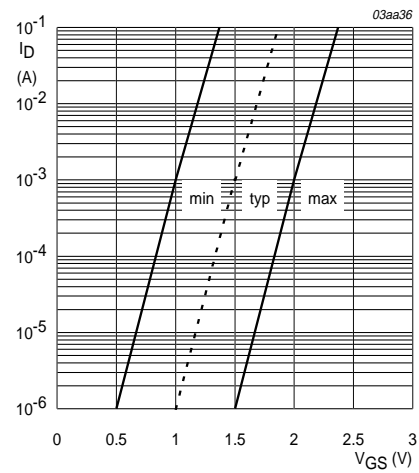
$$a = \frac{R_{DSon}}{R_{DSon}(25\text{ }^{\circ}\text{C})}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



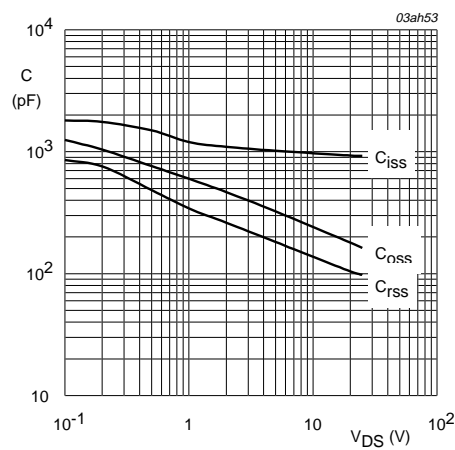
$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



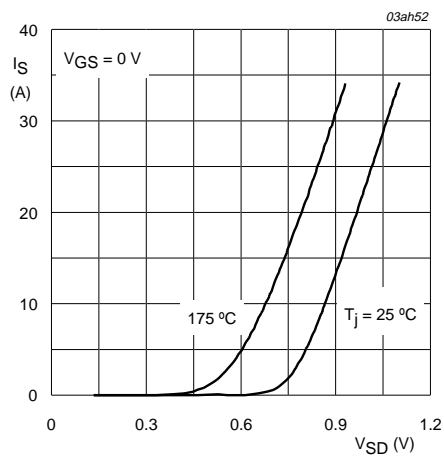
$T_j = 25 \text{ }^\circ\text{C}$; $V_{DS} = V_{GS}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



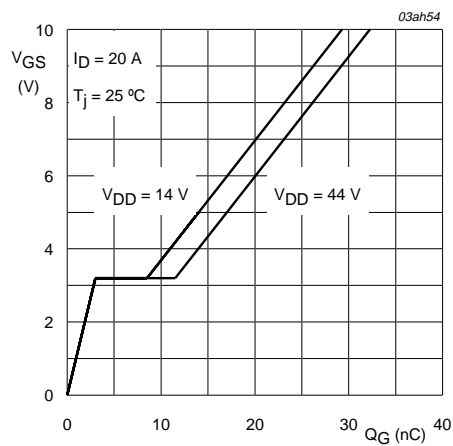
$V_{GS} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_J = 25\text{ }^{\circ}\text{C}$ and $175\text{ }^{\circ}\text{C}$; $V_{GS} = 0\text{ V}$

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



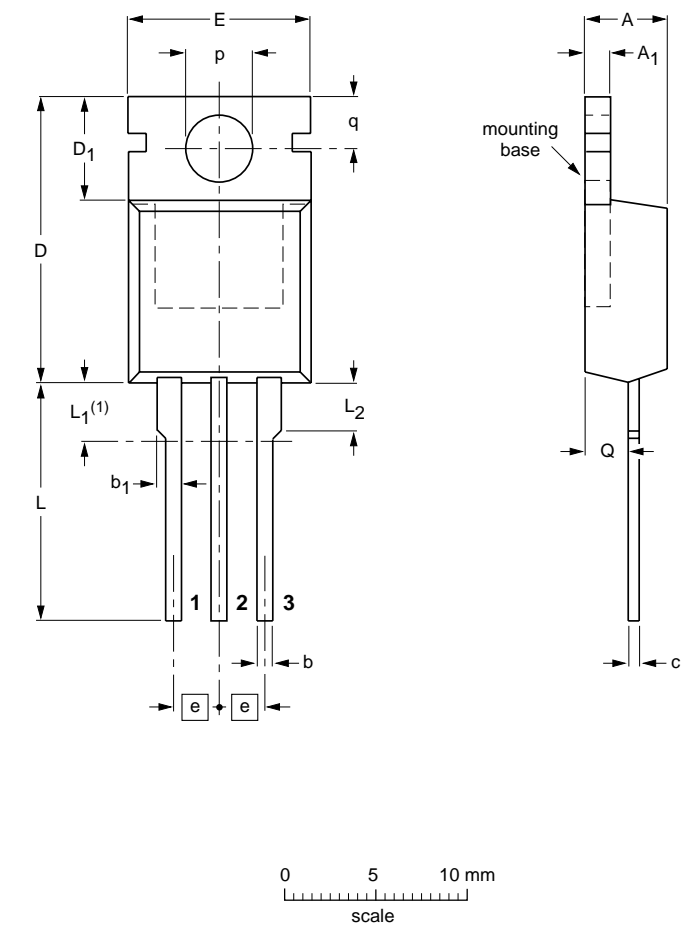
$T_J = 25\text{ }^{\circ}\text{C}$; $I_D = 20\text{ A}$

Fig 13. Gate-source voltage as a function of turn-on gate charge; typical values.

9. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

| UNIT | A | A ₁ | b | b ₁ | c | D | D ₁ | E | e | L | L ₁ (1) | L ₂ max. | p | q | Q |
|------|------------|----------------|------------|----------------|------------|--------------|----------------|-------------|------|--------------|--------------------|------------------------|------------|------------|------------|
| mm | 4.5 4.1 | 1.39 1.27 | 0.9 0.7 | 1.3 1.0 | 0.7 0.4 | 15.8 15.2 | 6.4 5.9 | 10.3 9.7 | 2.54 | 15.0 13.5 | 3.30 2.79 | 3.0 | 3.8 3.6 | 3.0 2.7 | 2.6 2.2 |

Note

1. Terminals in this zone are not tinned.


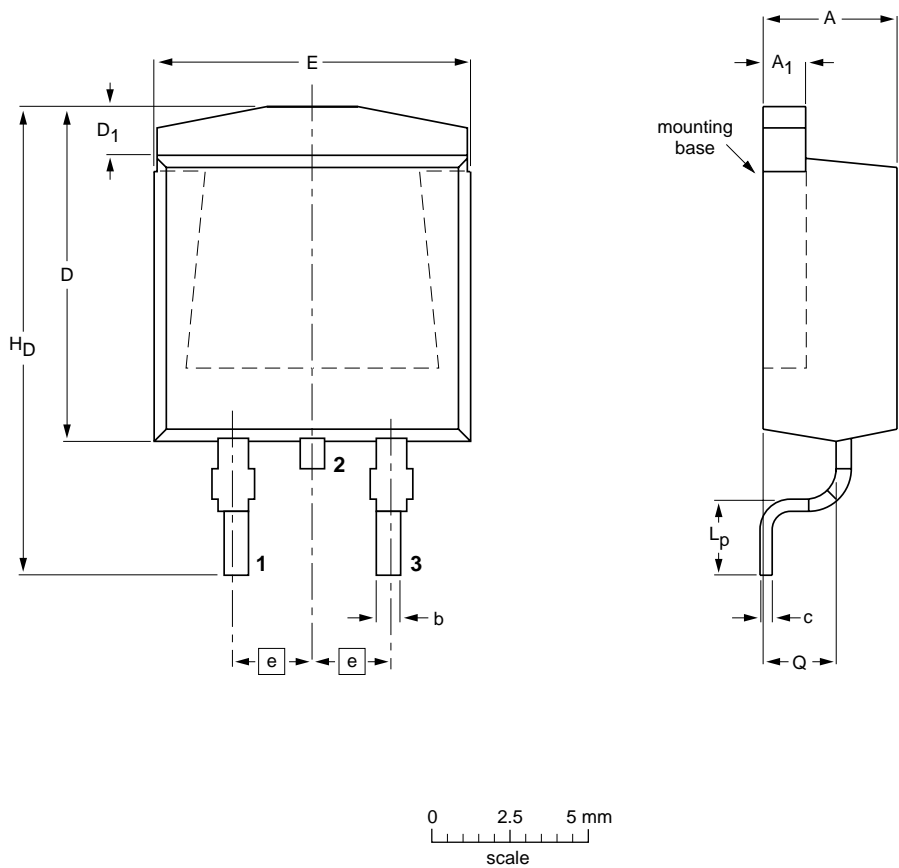
| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|--------------------|------------|-----------------|-------|--|---|----------------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT78 | | 3-lead TO-220AB | SC-46 | |  | 00-09-07 01-02-16 |

Fig 14. SOT78 (TO-220AB).

Plastic single-ended surface mounted package (Philips version of D²-PAK); 3 leads
(one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

| UNIT | A | A ₁ | b | c | D _{max.} | D ₁ | E | e | L _p | H _D | Q |
|------|--------------|----------------|--------------|--------------|-------------------|----------------|---------------|------|----------------|----------------|--------------|
| mm | 4.50 4.10 | 1.40 1.27 | 0.85 0.60 | 0.64 0.46 | 11 | 1.60 1.20 | 10.30 9.70 | 2.54 | 2.90 2.10 | 15.80 14.80 | 2.60 2.20 |

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|--------------------|------------|-------|------|--|------------------------|-----------------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT404 | | | | | | -99-06-25 01-02-12 |

Fig 15. SOT404 (D²-PAK).

10. Revision history

Table 6: Revision history

| Rev | Date | CPCN | Description |
|-----|----------|------|--------------------------------|
| 01 | 20011106 | - | Product data; initial version. |

11. Data sheet status

| Data sheet status ^[1] | Product status ^[2] | Definition |
|----------------------------------|-------------------------------|--|
| Objective data | Development | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice. |
| Preliminary data | Qualification | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product. |
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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